

Refine Search

10/086655

Search Results -

Terms	Documents
L2 and (second near2 oxide)	2

Database:

US Pre-Grant Publication Full-Text Database
 US Patents Full-Text Database
 US OCR Full-Text Database
 EPO Abstracts Database
 JPO Abstracts Database
 Derwent World Patents Index
 IBM Technical Disclosure Bulletins

Search:

L4

Refine Search

Recall Text

Clear

Interrupt

Search History

 DATE: Wednesday, December 31, 2003 [Printable Copy](#) [Create Case](#)
Set Name Query

side by side

Hit Count Set Name

result set

DB=USPT; PLUR=YES; OP=ADJ

<u>L4</u>	L2 and (second near2 oxide)	2	<u>L4</u>
<u>L3</u>	L2 and (wet adj tool)	0	<u>L3</u>
<u>L2</u>	L1 and mask and resist and (copper near2 seed)	34	<u>L2</u>
<u>L1</u>	interconnect and barrier and (plating near3 copper)	539	<u>L1</u>

END OF SEARCH HISTORY

Hit List

Clear	Generate Collection	Print	Fwd Refs	Bkwd Refs
Generate OACS				

Search Results - Record(s) 1 through 2 of 2 returned.

☐ 1. Document ID: US 6420262 B1

L4: Entry 1 of 2

File: USPT

Jul 16, 2002

US-PAT-NO: 6420262

DOCUMENT-IDENTIFIER: US 6420262 B1

TITLE: Structures and methods to enhance copper metallization

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw De
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☐ 2. Document ID: US 6376370 B1

L4: Entry 2 of 2

File: USPT

Apr 23, 2002

US-PAT-NO: 6376370

DOCUMENT-IDENTIFIER: US 6376370 B1

**** See image for Certificate of Correction ****

TITLE: Process for providing seed layers for using aluminum, copper, gold and silver metallurgy process for providing seed layers for using aluminum, copper, gold and silver metallurgy

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw De
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Clear	Generate Collection	Print	Fwd Refs	Bkwd Refs	Generate OACS
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Terms	Documents
L2 and (second near2 oxide)	2

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Refine Search

Search Results -

Terms	Documents
L12 and patterning	3

Database:

US Pre-Grant Publication Full-Text Database
 US Patents Full-Text Database
 US OCR Full-Text Database
 EPO Abstracts Database
 JPO Abstracts Database
 Derwent World Patents Index
 IBM Technical Disclosure Bulletins

Search:

L13

Search History

DATE: Wednesday, December 31, 2003 [Printable Copy](#) [Create Case](#)

<u>Set Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u> result set
<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<u>L13</u>	L12 and patterning	3	<u>L13</u>
<u>L12</u>	L11 and etching	8	<u>L12</u>
<u>L11</u>	L10 and oxides	15	<u>L11</u>
<u>L10</u>	L8 and interconnect and barrier and (copper adj seed) and plating	16	<u>L10</u>
<u>L9</u>	L8 and interconnect and barrier and (copper adj seed) and plating and (second near2 oxide)	0	<u>L9</u>
<u>L8</u>	tool adj set	4771	<u>L8</u>
<u>L7</u>	(wet adj tool adj set)	1	<u>L7</u>
<u>L6</u>	L1 and (wet adj tool adj set)	0	<u>L6</u>
<u>L5</u>	L2 and (wet adj tool adj set)	0	<u>L5</u>
<u>L4</u>	L2 and (second near2 oxide)	2	<u>L4</u>
<u>L3</u>	L2 and (wet adj tool)	0	<u>L3</u>
<u>L2</u>	L1 and mask and resist and (copper near2 seed)	34	<u>L2</u>

L1 interconnect and barrier and (plating near3 copper)

539 L1

END OF SEARCH HISTORY

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Generate OACS				

Search Results - Record(s) 1 through 3 of 3 returned.

☐ 1. Document ID: US 6387800 B1

L13: Entry 1 of 3

File: USPT

May 14, 2002

US-PAT-NO: 6387800

DOCUMENT-IDENTIFIER: US 6387800 B1

TITLE: Method of forming barrier and seed layers for electrochemical deposition of copper

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw D
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☐ 2. Document ID: US 6143126 A

L13: Entry 2 of 3

File: USPT

Nov 7, 2000

US-PAT-NO: 6143126

DOCUMENT-IDENTIFIER: US 6143126 A

TITLE: Process and manufacturing tool architecture for use in the manufacture of one or more metallization levels on an integrated circuit

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw D
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☐ 3. Document ID: US 6120641 A

L13: Entry 3 of 3

File: USPT

Sep 19, 2000

US-PAT-NO: 6120641

DOCUMENT-IDENTIFIER: US 6120641 A

TITLE: Process architecture and manufacturing tool sets employing hard mask patterning for use in the manufacture of one or more metallization levels on a workpiece

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw D
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Clear	Generate Collection	Print	Fwd Refs	Bkwd Refs	Generate OACS
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Terms	Documents
L12 and patterning	3

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Search Results - Record(s) 1 through 8 of 8 returned.

☐ 1. Document ID: US 6645356 B1

L12: Entry 1 of 8

File: USPT

Nov 11, 2003

US-PAT-NO: 6645356

DOCUMENT-IDENTIFIER: US 6645356 B1

TITLE: Methods and apparatus for processing the surface of a microelectronic workpiece

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw D
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☐ 2. Document ID: US 6387800 B1

L12: Entry 2 of 8

File: USPT

May 14, 2002

US-PAT-NO: 6387800

DOCUMENT-IDENTIFIER: US 6387800 B1

TITLE: Method of forming barrier and seed layers for electrochemical deposition of copper

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw D
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☐ 3. Document ID: US 6376374 B1

L12: Entry 3 of 8

File: USPT

Apr 23, 2002

US-PAT-NO: 6376374

DOCUMENT-IDENTIFIER: US 6376374 B1

TITLE: Process and manufacturing tool architecture for use in the manufacturing of one or more protected metallization structures on a workpiece

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw D
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☐ 4. Document ID: US 6309524 B1

L12: Entry 4 of 8

File: USPT

Oct 30, 2001

US-PAT-NO: 6309524

DOCUMENT-IDENTIFIER: US 6309524 B1

**** See image for Certificate of Correction ****

TITLE: Methods and apparatus for processing the surface of a microelectronic workpiece

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw. De
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☐ 5. Document ID: US 6309520 B1

L12: Entry 5 of 8

File: USPT

Oct 30, 2001

US-PAT-NO: 6309520

DOCUMENT-IDENTIFIER: US 6309520 B1

**** See image for Certificate of Correction ****

TITLE: Methods and apparatus for processing the surface of a microelectronic workpiece

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw. De
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☐ 6. Document ID: US 6303010 B1

L12: Entry 6 of 8

File: USPT

Oct 16, 2001

US-PAT-NO: 6303010

DOCUMENT-IDENTIFIER: US 6303010 B1

**** See image for Certificate of Correction ****

TITLE: Methods and apparatus for processing the surface of a microelectronic workpiece

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw. De
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☐ 7. Document ID: US 6143126 A

L12: Entry 7 of 8

File: USPT

Nov 7, 2000

US-PAT-NO: 6143126

DOCUMENT-IDENTIFIER: US 6143126 A

TITLE: Process and manufacturing tool architecture for use in the manufacture of one or more metallization levels on an integrated circuit

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw. De
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☐ 8. Document ID: US 6120641 A

L12: Entry 8 of 8

File: USPT

Sep 19, 2000

US-PAT-NO: 6120641

DOCUMENT-IDENTIFIER: US 6120641 A

TITLE: Process architecture and manufacturing tool sets employing hard mask patterning for use in the manufacture of one or more metallization levels on a workpiece

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw. D
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Terms	Documents
L11 and etching	8

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